



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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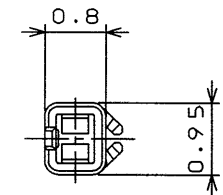
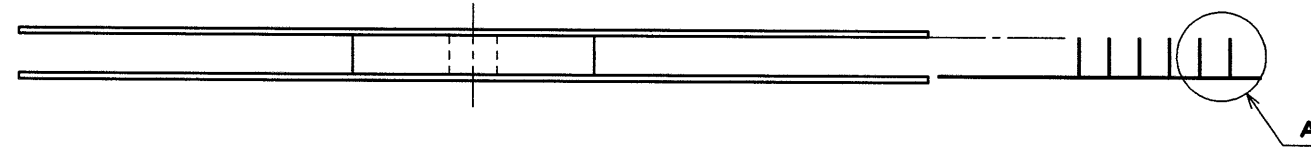
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



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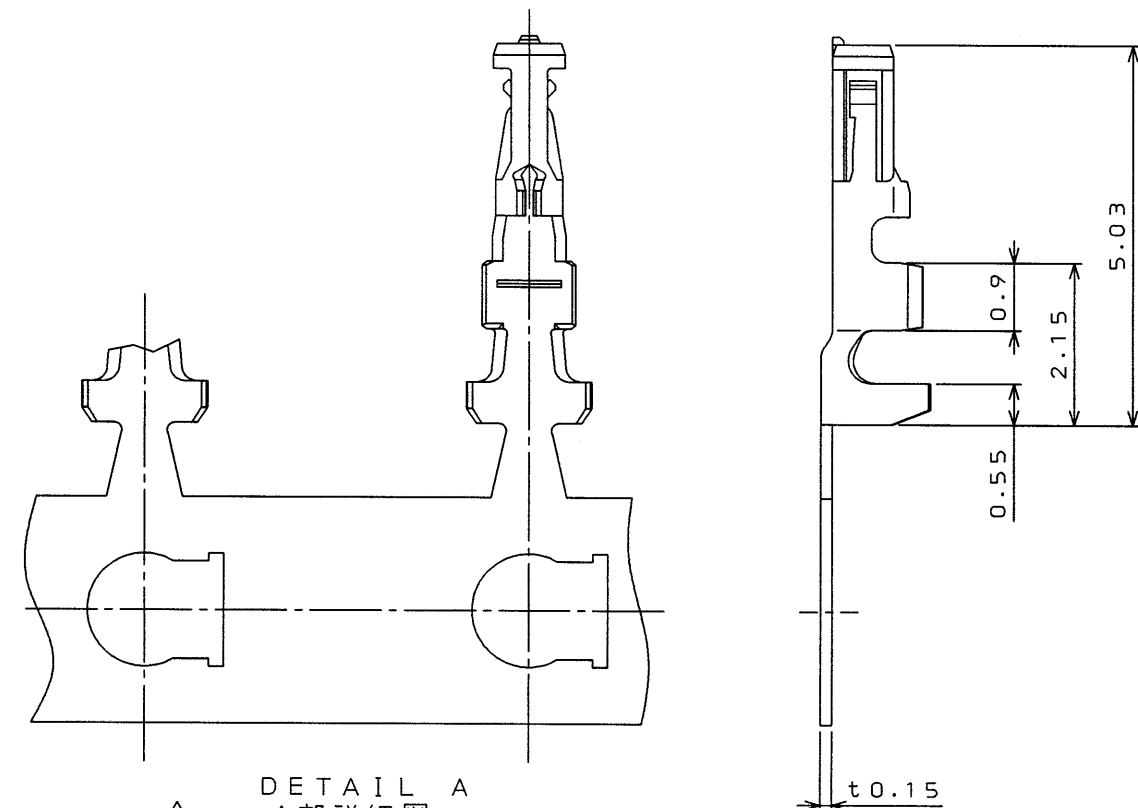
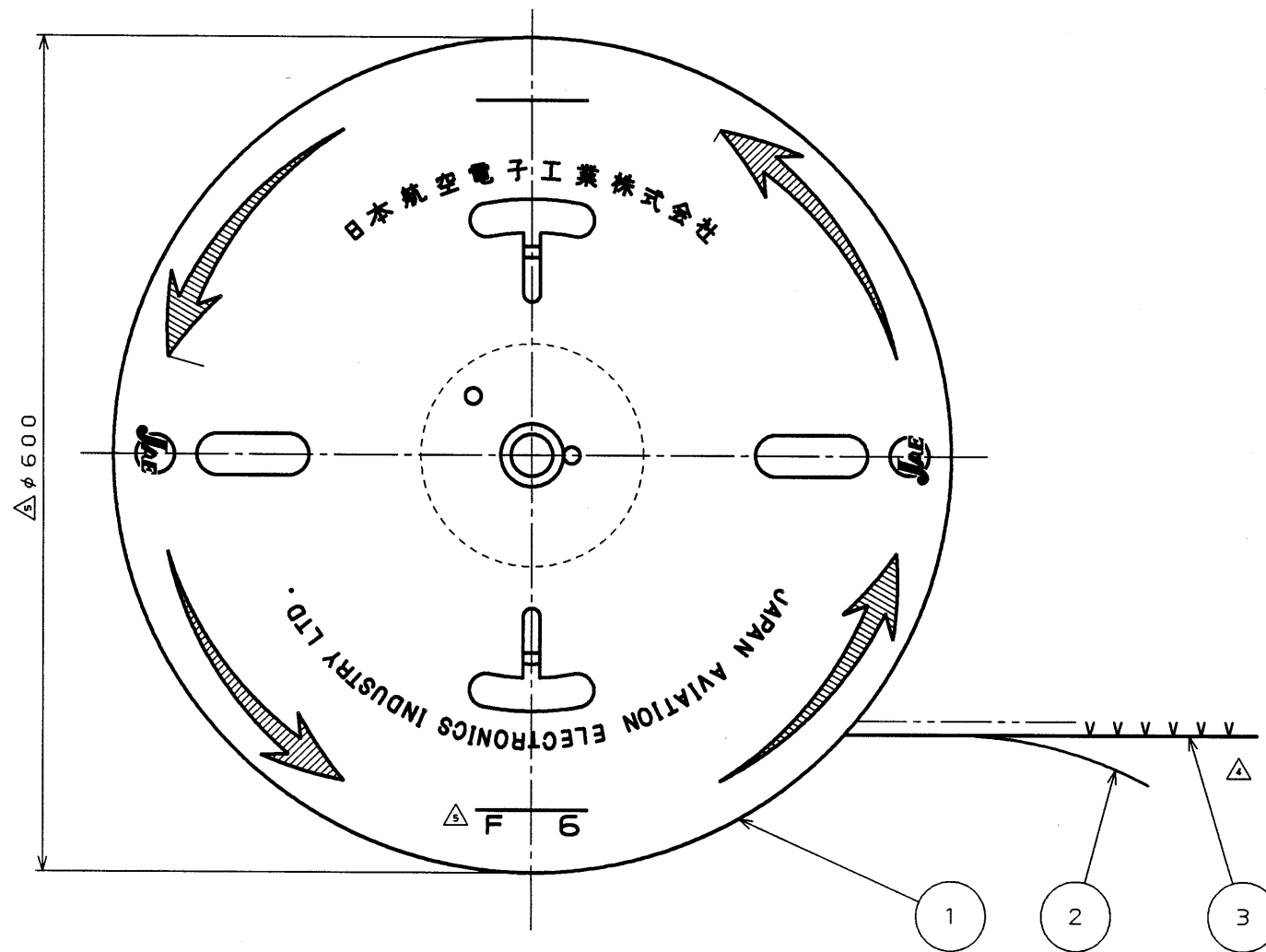
('ON 0NIMVHD) 台 集 理 図

版 数 REV.	年 月 日 DATE	DCN NO.	変 更 内 容 DESCRIPTION	製 図 DR.	担 当 CHK.	査 閲 APPD.	承 認 APPD.
2	4.Apr.1996	37758	REVISED PART NUMBER.	M.OOWA	K.HISAMATSU	K.IBARAKI	T.MORINO
3	13.Nov.1996	39034	ADDED JAPANESE. 日本語追記		K.HISAMATSU	K.IBARAKI	T.MORINO
4	27.Mar.1998	41810	DELETED MARK. 記号削除	M.HIGUCHI	K.HISAMATSU	H.AMEMIYA	H.FUJINO
5	28.Oct.1999	44974	REVISED DIMENSION REEL DIA. リール径寸法変更	M.ABE	H.OBIKANE	K. Hisatomi	H. Amemiya



EXCLUDING CRIMP POT

クリンプポット部は除く



△ A 部詳細図
(SCALE 10:1)
△ (尺度 10:1)

NOTE 1. APPLICABLE WIRE: #28~#32 AWG. STANDERD.
APPLICABLE WIRE INSULATION OUTER
DIA. 0.5~0.9mm.

注 1. 使用電線は、AWG#28~#32の撚線とし、
仕上り外径φ0.9~φ0.5とする。

符号 NO.	名 称 DESCRIPTION	個 数 QTY.	材 料 MATERIAL	仕 上 FINISH	備 考 REMARKS
3	CONTACT コンタクト	15000	PHOSPHOR BRONZE リン青銅	GOLD OVER NICKEL Ni上Auメッキ	
2	PAPER TAPE 紙リール	1	PAPER		
1	MAGAZINE マガジン	1	PAPER		
仕 様 書 (SPECIFICATION)		第 1 版 (ORIGINAL DATE) 8.Feb.1996		尺 寸 (SCALE) 1:1	
製 図 DR.		担 当 CHK. K.HISAMATSU		名 称 (TITLE) △ FI-C3-A1-15000	
査 閲 APPD. K.IBARAKI		承 認 APPD. T.MORINO		MAGAZINE ASSEMBLY (マガジンアッセンブリ)	
重 量 (WEIGHT)		製 図 DR.		備 考 REMARKS 日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.	
図 面 番 号 (DRAWING NO.)		版 数 (REV.)		S I Z E A 3	
SJ030670		5		JAE CONNECTOR.COM Reference Only	

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